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SERIAL NUMBER 10/826,752	FILING OR 371(c) DATE 04/16/2004 RULE	CLASS 438	GROUP ART UNIT 2813	ATTORNEY DOCKET NO.
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APPLICANTS

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** CONTINUING DATA *****

This application is a DIV of 10/315,534 12/10/2002 PAT 6,732,913
and is a CIP of 09/843,248 04/26/2001 PAT 6,592,019

** FOREIGN APPLICATIONS *****

SINGAPORE 200107810-4 12/10/2001

IF REQUIRED, FOREIGN FILING LICENSE GRANTED ** SMALL ENTITY **

** 06/25/2004

Foreign Priority claimed	<input type="checkbox"/> yes <input type="checkbox"/> no	STATE OR COUNTRY SINGAPORE	SHEETS DRAWING 12	TOTAL CLAIMS 18	INDEPENDENT CLAIMS 2
35 USC 119 (a-d) conditions met	<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance				

ADDRESS

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TITLE

Method for forming a wafer level chip scale package, and package formed thereby

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